

RELIABILITY MONITOR

PRODUCT	MONITOR DATE	DATE CODE	ASSEMBLY FACILITY	ASSEMBLY LOT NO	PROCESS TYPE	PACKAGE TYPE
DS12887 (w/BR1225)	Oct-97	9651 A2	DALLAS	DA89005-1	N/A	24 MODULE

STRESS/JOB NO.

**READPOINT
(Sample Size/No. of Fails)**

Hi Temp Storage
85°C, No Bias
P-20684

48 Hr
200/0

Cum %
0.0%

Temp Cycle
0°C to +70°C
P-20701

300 ~ 1K ~
100/0

Cum %

Biased Moisture
85°C/85% RH, 5.5 V.
P-20702

274 Hr 959 Hr
100/0 100/0

Cum %
0.0%

Phys. Dimen.
P-20683
6/0

Solderability
P-20682

Failure Mode

Failure Analysis